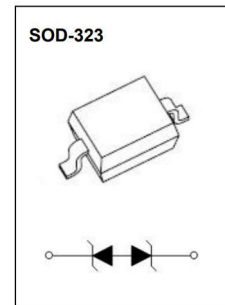


Features

Bi-directional ESD protection of one line
Reverse stand-off voltage: 6V
Low reverse clamping voltage
Low leakage current
Fast response time
IEC 61000-4-2 (ESD) immunity test :
Air discharge: ±30kV
Contact discharge: ±30kV

Applications

Computers and peripherals
High speed data lines
Audio and video equipment
Cellular handsets and accessories
Subscriber identity module(SIM) card protection
Portable electronics
FireWire
Other electronics equipments communi- cation systems



Absolute Maximum Rating

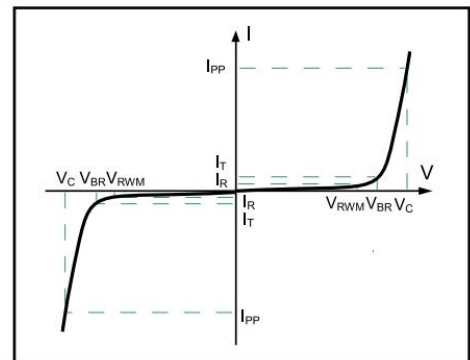
Parameter	Symbol	Value	Unit
Peak Pulse Power (8/20μs)	Ppk	350	W
Peak Pulse Current (8/20μs)	IPP	25	A
ESD per IEC 61000-4-2 (Air)	VESD	±30	kV
ESD per IEC 61000-4-2 (Contact)		±30	
Operating Temperature Range	TJ	-55to +125	°C
Storage Temperature Range	Tstg	-55 to +150	°C

Electrical Characteristics

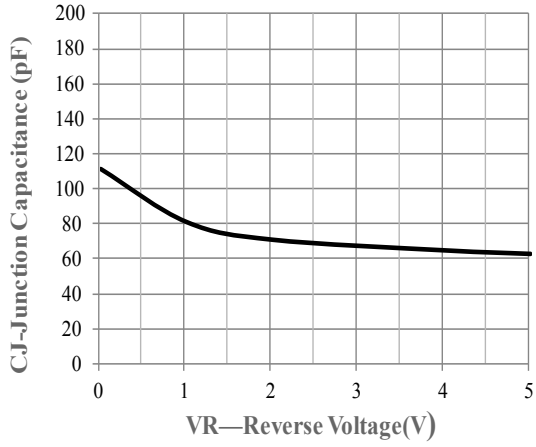
Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Reverse Working Voltage	V_{RWM}				6	V
Breakdown Voltage	V_{BR}	$I_T = 1mA$	6.5		8	V
Reverse Leakage Current	I_R	$V_{RWM} = \pm 5V$			0.5	μA
Clamping Voltage	V_C	$I_{PP} = 25A$ (8 x 20 μs pulse)			13	V
Junction Capacitance	C_j	$V_R = 0V, f = 1MHz$			110	pF

Electrical Parameter

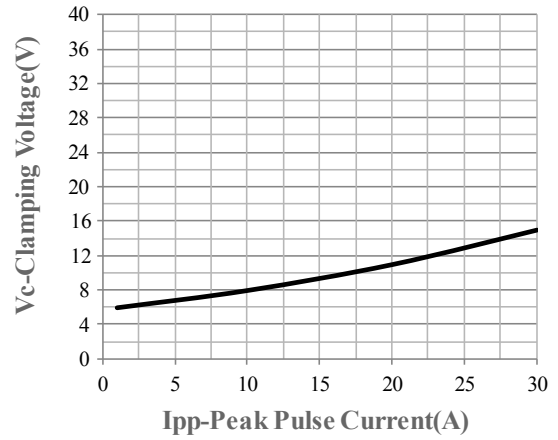
Symbol	Parameter
I_T	Test Current
I_{PP}	Maximum Reverse Peak Pulse Current
V_C	Clamping Voltage @ I_C
V_{BR}	Breakdown Voltage @ I_T
I_R	Reverse Leakage Current @ V_{RWM}
V_{RWM}	Reverse Standoff Voltage



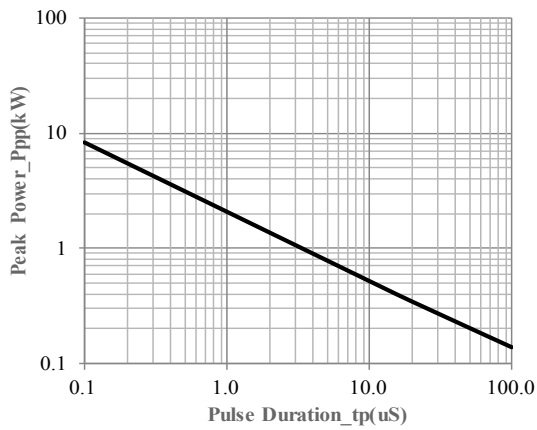
RATING AND CHARACTERISTIC CURVES



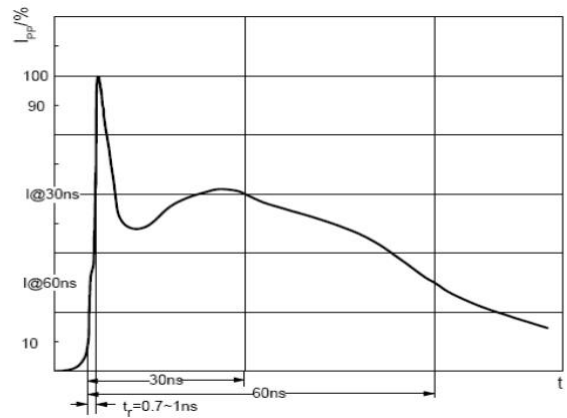
Junction Capacitance vs. Reverse Voltage



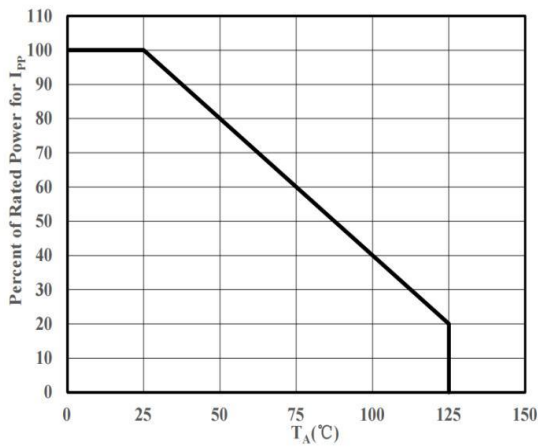
Clamping Voltage vs. Peak Pulse Current



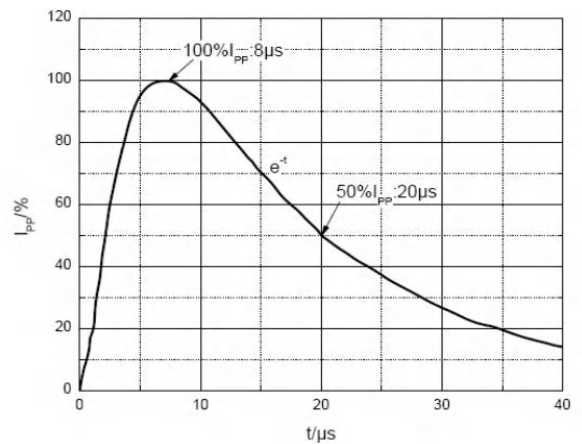
Peak Pulse Power vs. Pulse Time



ESD pulse waveform according to IEC61000-4-2



Power Derating Curve



8/20uS pulse waveform according to IEC 61000-4-5

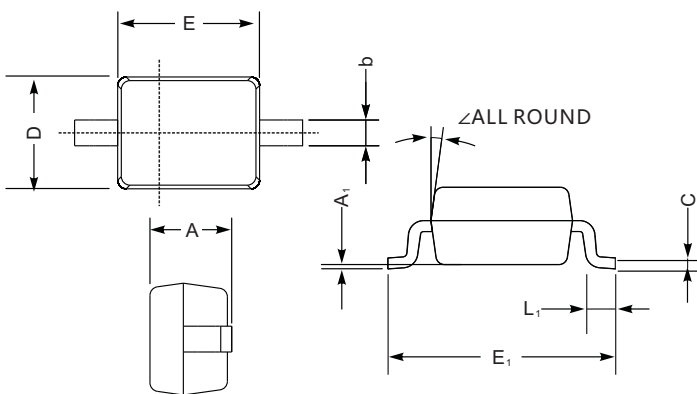
Soldering parameters

Reflow Condition		Pb-Free assembly (see as below)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150°C
	-Temperature Max($T_{s(max)}$)	+200°C
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3°C/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/sec. Max
Reflow	-Temperature(T_L)(Liquid us)	+217°C
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_P)		+260(+0/-5)°C
Time within 5°C of actual Peak Temp (t_p)		30 secs. Max
Ramp-down Rate		6°C/sec. Max
Time 25°C to Peak Temp (T_P)		8 min. Max
Do not exceed		+260°C



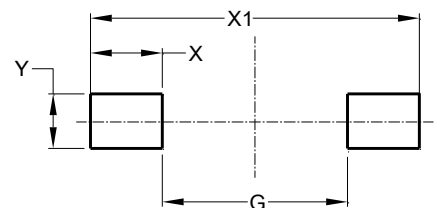
Package Dimensions & Suggested Pad Layout

SOD323



SOD-323 mechanical data

UNIT		A	C	D	E	E ₁	b	L ₁	A ₁	∠
mm	max	1.1	0.15	1.4	1.8	2.75	0.4	0.45	0.2	9°
	min	0.8	0.08	1.2	1.4	2.55	0.25	0.2	—	
mil	max	43	5.9	55	70	108	16	16	8	
	min	32	3.1	47	63	100	9.8	7.9	—	



Dimensions	Value (in mm)
G	1.40
X	1.20
X1	3.80
Y	1.00

Tape & reel specification

Tape		Symbol	Dimension (mm)		
		P0	4.00±0.20		
		P1	4.00±0.20		
		P2	2.00±0.20		
		D0	1.55±0.20		
		D1	1.00±0.20		
		E	1.55±0.25		
		F	3.60±0.20		
		W	8.00±0.20		
		A0	2.00±0.20		
		B0	3.25±0.20		
		K0	1.35±0.20		
		T	0.23±0.10		
		7" Reel		D2	177.0±5.0
				D3	55Min.
D4	R24.6±2.0				
G	R82.0±2.0				
I	13.0±2.0				
W1	10.20±3.0				
		Quantity: 3000PCS			